

CNY171M, CNY172M, CNY173M, CNY174M, CNY17F1M, CNY17F2M, CNY17F3M, CNY17F4M, MOC8106M, MOC8107M Phototransistor Optocouplers

Features

- UL recognized (File # E90700, Vol. 2)
- VDE recognized
 - Add option V (e.g., CNY17F2VM)
 - File #102497
- Current transfer ratio in select groups
- High BV_{CEO} : 70V minimum (CNY17XM, CNY17FXM, MOC810XM)
- Closely matched current transfer ratio (CTR) minimizes unit-to-unit variation.
- Very low coupled capacitance along with no chip to pin 6 base connection for minimum noise susceptibility (CNY17FXM, MOC810XM)

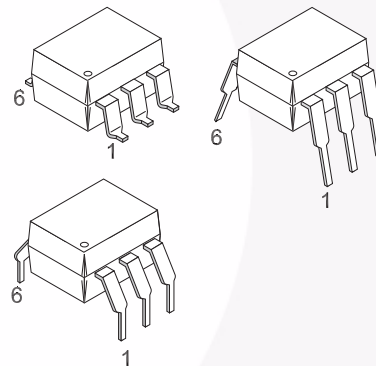
Applications

- Power supply regulators
- Digital logic inputs
- Microprocessor inputs
- Appliance sensor systems
- Industrial controls

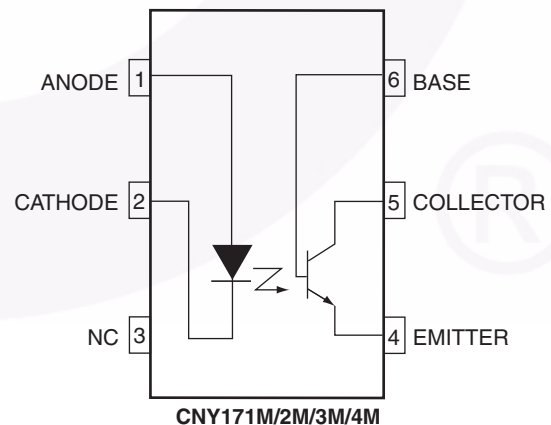
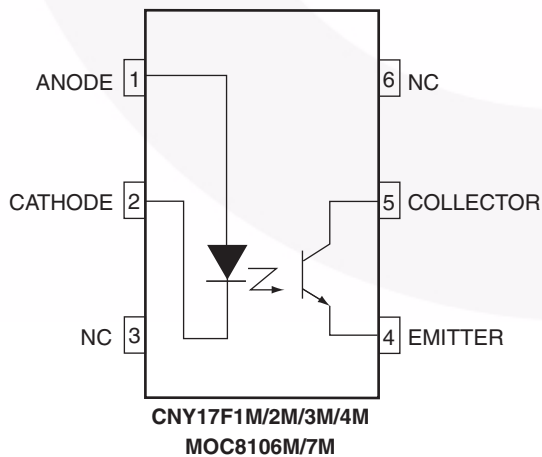
Description

The CNY17XM, CNY17FXM and MOC810XM devices consist of a Gallium Arsenide IRED coupled with an NPN phototransistor in a dual in-line package.

Package Outlines



Schematics



Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameters	Value	Units
TOTAL DEVICE			
T _{STG}	Storage Temperature	-40 to +150	°C
T _{OPR}	Operating Temperature	-40 to +100	°C
T _{SOL}	Lead Solder Temperature	260 for 10 sec	°C
P _D	Total Device Power Dissipation @ 25°C (LED plus detector) Derate Linearly From 25°C	250	mW
		2.94	mW/°C
EMITTER			
I _F	Continuous Forward Current	60	mA
V _R	Reverse Voltage	6	V
I _F (pk)	Forward Current – Peak (1µs pulse, 300pps)	1.5	A
P _D	LED Power Dissipation 25°C Ambient Derate Linearly From 25°C	120	mW
		1.41	mW/°C
DETECTOR			
I _C	Continuous Collector Current	50	mA
V _{CEO}	Collector-Emitter Voltage	70	V
V _{ECO}	Emitter Collector Voltage	7	V
P _D	Detector Power Dissipation @ 25°C Derate Linearly from 25°C	150	mW
		1.76	mW/°C

Electrical Characteristics (T_A = 25°C Unless otherwise specified.)⁽¹⁾

Individual Component Characteristics

Symbol	Parameters	Test Conditions	Device	Min.	Typ.	Max.	Units
EMITTER							
V _F	Input Forward Voltage	I _F = 60mA	CNY17XM, CNY17FXM	1.0	1.35	1.65	V
		I _F = 10mA	MOC810XM	1.0	1.15	1.50	
C _J	Capacitance	V _F = 0 V, f = 1.0MHz	All		18		pF
I _R	Reverse Leakage Current	V _R = 6V	All		0.001	10	μA
DETECTOR							
BV _{CEO}	Breakdown Voltage Collector to Emitter	I _C = 1.0mA, I _F = 0	All	70	100		V
BV _{CBO}	Collector to Base	I _C = 10μA, I _F = 0	CNY171M/2M/3M/4M	70	120		
BV _{ECO}	Emitter to Collector	I _E = 100μA, I _F = 0	All	7	10		
I _{CEO}	Leakage Current Collector to Emitter	V _{CE} = 10 V, I _F = 0	All		1	50	nA
I _{CBO}	Collector to Base	V _{CB} = 10 V, I _F = 0	CNY171M/2M/3M/4M			20	nA
C _{CE}	Capacitance Collector to Emitter	V _{CE} = 0, f = 1MHz	All		8		pF
C _{CB}	Collector to Base	V _{CB} = 0, f = 1MHz	CNY171M/2M/3M/4M		20		pF
C _{EB}	Emitter to Base	V _{EB} = 0, f = 1MHz	CNY171M/2M/3M/4M		10		pF

Isolation Characteristics

Symbol	Characteristic	Test Conditions	Min.	Typ.*	Max.	Units
V _{ISO}	Input-Output Isolation Voltage	f = 60 Hz, t = 1 sec., I _{I-O} ≤ 2μA ⁽⁴⁾	7500			Vac(pk)
R _{ISO}	Isolation Resistance	V _{I-O} = 500 VDC ⁽⁴⁾	10 ¹¹			Ω
C _{ISO}	Isolation Capacitance	V _{I-O} = ∅, f = 1MHz ⁽⁴⁾		0.2		pF

Transfer Characteristics (T_A = 25°C Unless otherwise specified.)⁽³⁾

Symbol	DC Characteristics	Test Conditions	Min.	Typ.*	Max.	Units	
COUPLED							
(CTR) ⁽²⁾	Output Collector Current	MOC8106M	I _F = 10mA, V _{CE} = 10V		50	%	
		MOC8107M			100		
		CNY17F1M	I _F = 10mA, V _{CE} = 5V		40		80
		CNY17F2M			63		125
		CNY17F3M			100		200
		CNY17F4M			160		320
		CNY171M			40		80
		CNY172M			63		125
		CNY173M			100		200
		CNY174M			160		320
V _{CE(sat)}	Collector-Emitter Saturation Voltage	CNY17XM/FXM	I _C = 2.5mA, I _F = 10mA		0.4	V	
		MOC8106M/7M	I _C = 500μA, I _F = 5.0mA				

*All typicals at T_A = 25°C

Electrical Characteristics (Continued) ($T_A = 25^\circ\text{C}$ Unless otherwise specified.)⁽¹⁾**Transfer Characteristics** (Continued)⁽³⁾

Symbol	AC Characteristics ⁽⁴⁾		Test Conditions	Min.	Typ.*	Max.	Units
NON-SATURATED SWITCHING TIME							
t_{on}	Turn-On Time	All Devices	$I_C = 2.0\text{mA}$, $V_{CC} = 10\text{V}$, $R_L = 100\Omega$		2	10	μs
t_{off}	Turn-Off Time	All Devices	$I_C = 2.0\text{mA}$, $V_{CC} = 10\text{V}$, $R_L = 100\Omega$		3	10	μs
t_d	Delay Time	CNY17XM/XFM	$I_F = 10\text{mA}$, $V_{CC} = 5\text{V}$, $R_L = 75\Omega$			5.6	μs
t_r	Rise Time	All Devices	$I_C = 2.0\text{mA}$, $V_{CC} = 10\text{V}$, $R_L = 100\Omega$		1		μs
		CNY17XM/FXM	$I_F = 10\text{mA}$, $V_{CC} = 5\text{V}$, $R_L = 75\Omega$			4.0	
t_s	Storage Time	CNY17XM/FXM	$I_F = 10\text{mA}$, $V_{CC} = 5\text{V}$, $R_L = 75\Omega$			4.1	μs
t_f	Fall Time	All Devices	$I_C = 2.0\text{mA}$, $V_{CC} = 10\text{V}$, $R_L = 100\Omega$		2		μs
		CNY17XM/FXM	$I_F = 10\text{mA}$, $V_{CC} = 5\text{V}$, $R_L = 75\Omega$			3.5	
SATURATED SWITCHING TIMES							
t_{on}	Turn-on Time	CNY171M/F1M	$I_F = 20\text{mA}$, $V_{CC} = 5\text{V}$, $R_L = 1\text{k}\Omega$			5.5	μs
		CNY172M/3M/4M CNY17F2M/F3M/F4M	$I_F = 10\text{mA}$, $V_{CC} = 5\text{V}$, $R_L = 1\text{k}\Omega$			8.0	
t_r	Rise Time	CNY171M/F1M	$I_F = 20\text{mA}$, $V_{CC} = 5\text{V}$, $R_L = 1\text{k}\Omega$			4.0	μs
		CNY172M/3M/4M CNY17F2M/F3M/F4M	$I_F = 10\text{mA}$, $V_{CC} = 5\text{V}$, $R_L = 1\text{k}\Omega$			6.0	
t_d	Delay Time	CNY171M/F1M	$I_F = 20\text{mA}$, $V_{CC} = 5\text{V}$, $R_L = 1\text{k}\Omega$			5.5	μs
		CNY172M/3M/4M CNY17F2M/F3M/F4M	$I_F = 10\text{mA}$, $V_{CC} = 5\text{V}$, $R_L = 1\text{k}\Omega$			8.0	
t_{off}	Turn-off Time	CNY171M/F1M	$I_F = 20\text{mA}$, $V_{CE} = 0.4\text{V}$			34	μs
		CNY172M/3M/4M CNY17F2M/F3M/F4M	$I_F = 10\text{mA}$, $V_{CE} = 0.4\text{V}$			39	
t_f	Fall Time	CNY171M/F1M	$I_F = 20\text{mA}$, $V_{CC} = 5\text{V}$, $R_L = 1\text{k}\Omega$			20.0	μs
		CNY172M/3M/4M CNY17F2M/F3M/F4M	$I_F = 10\text{mA}$, $V_{CC} = 5\text{V}$, $R_L = 1\text{k}\Omega$			24.0	
t_s	Storage Time	CNY171M/F1M	$I_F = 20\text{mA}$, $V_{CC} = 5\text{V}$, $R_L = 1\text{k}\Omega$			34.0	μs
		CNY172M/3M/4M CNY17F2M/F3M/F4M	$I_F = 10\text{mA}$, $V_{CC} = 5\text{V}$, $R_L = 1\text{k}\Omega$			39.0	

*All typicals at $T_A = 25^\circ\text{C}$ **Notes:**

1. Always design to the specified minimum/maximum electrical limits (where applicable).
2. Current Transfer Ratio (CTR) = $I_C/I_F \times 100\%$.
3. For test circuit setup and waveforms, refer to Figures 10 and 11.
4. For this test, Pins 1 and 2 are common, and Pins 4 and 5 are common.

Typical Performance Characteristics

Fig. 1 Normalized CTR vs. Forward Current

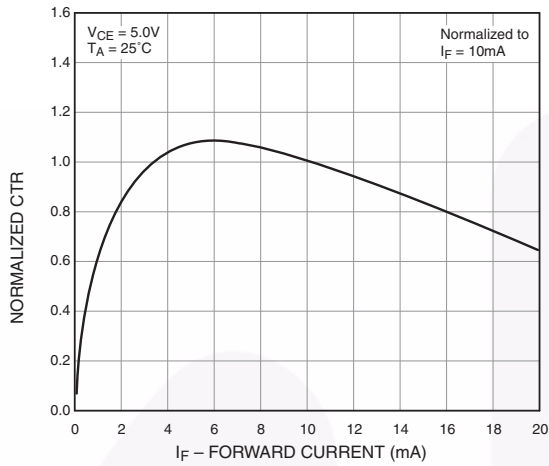


Fig. 2 Normalized CTR vs. Ambient Temperature

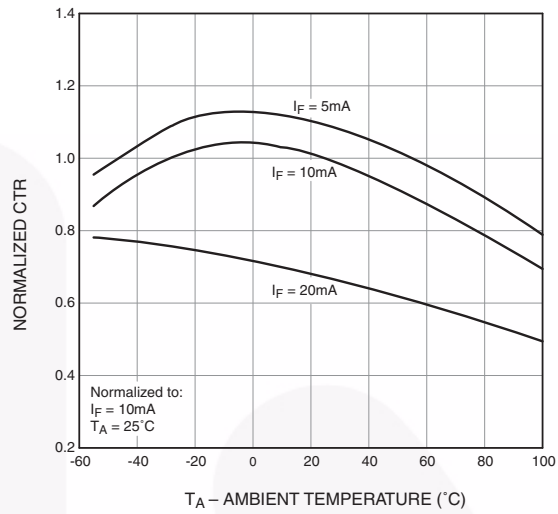


Fig. 3 CTR vs. RBE (Unsaturated)

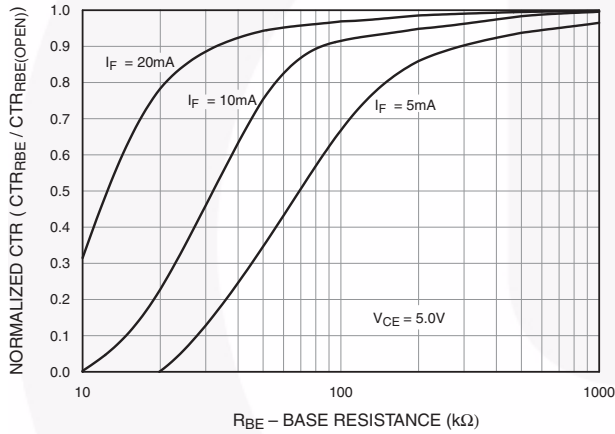


Fig. 4 CTR vs. RBE (Saturated)

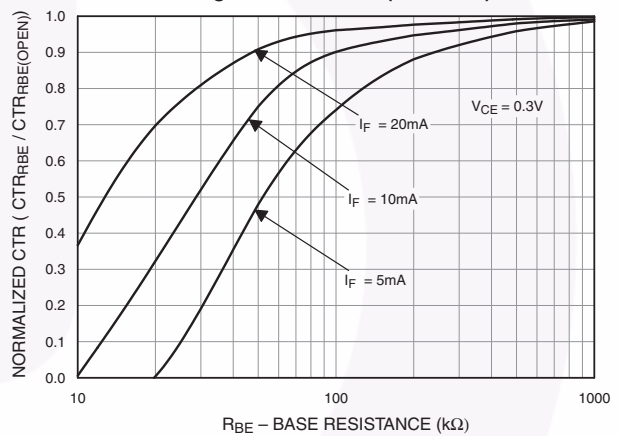


Fig. 5 Switching Speed vs. Load Resistor

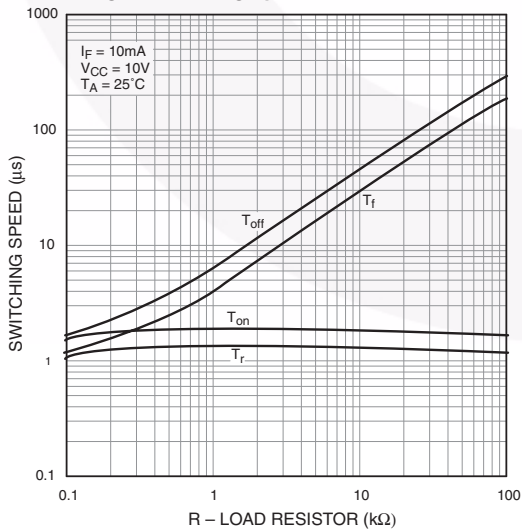
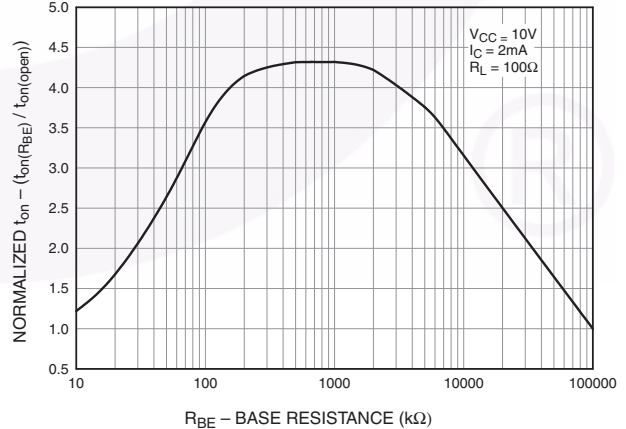
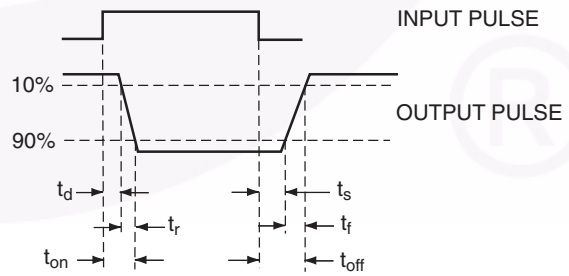
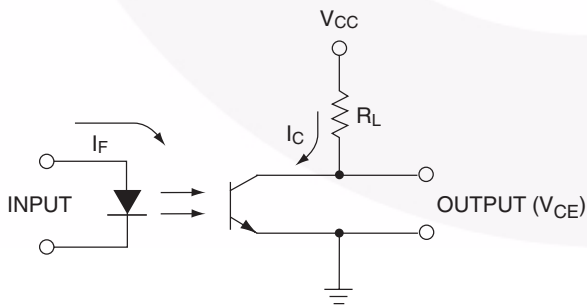
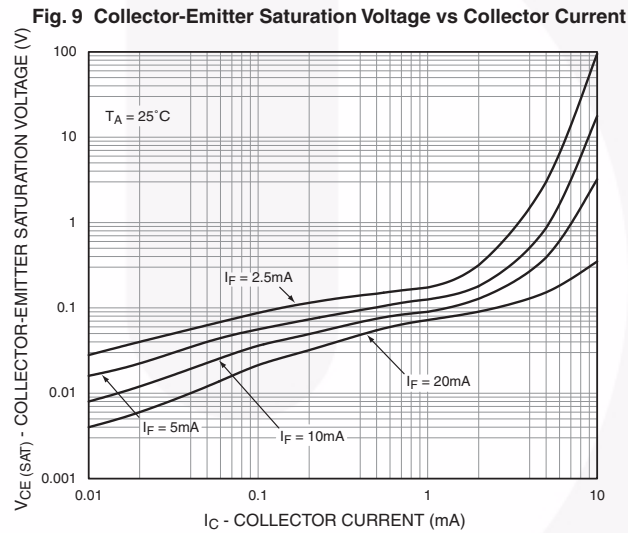
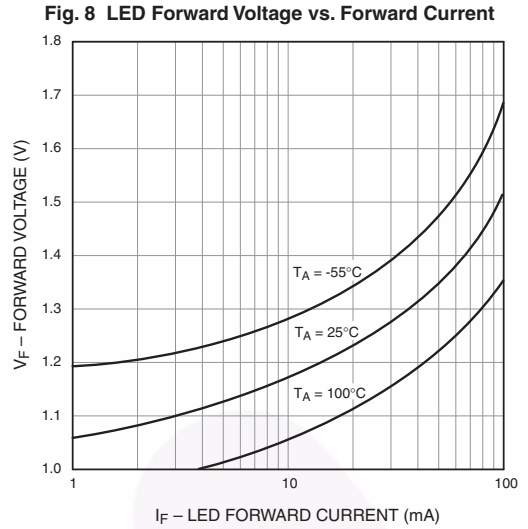
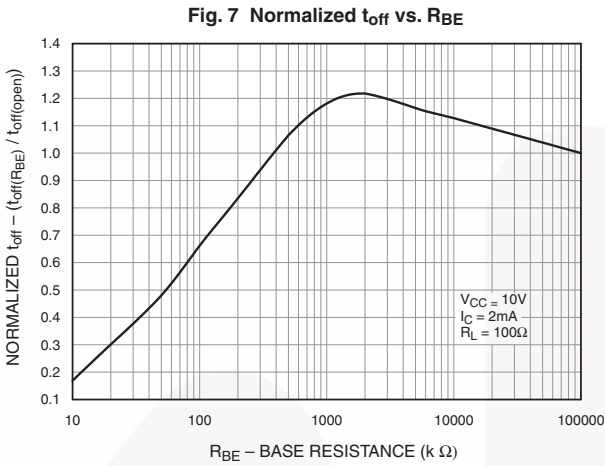


Fig. 6 Normalized ton vs. RBE

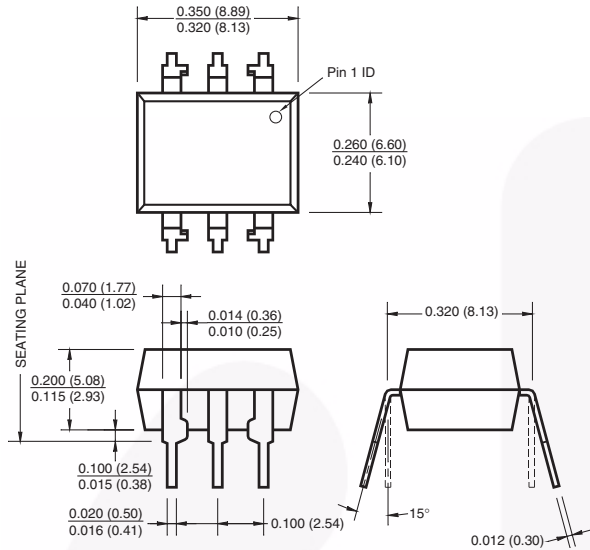


Typical Performance Characteristics (Continued)

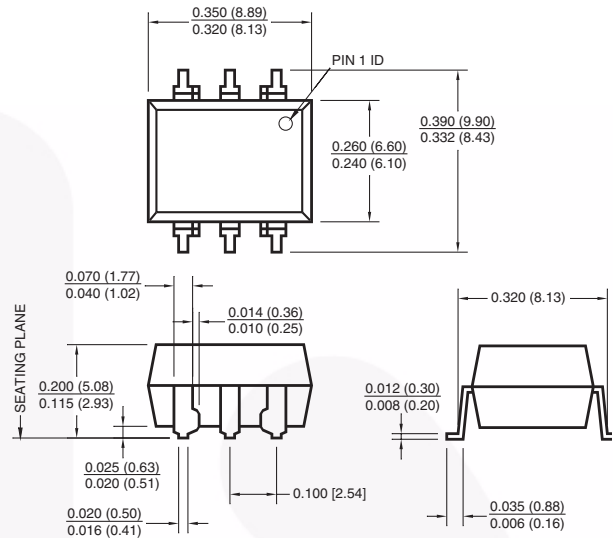


Package Dimensions

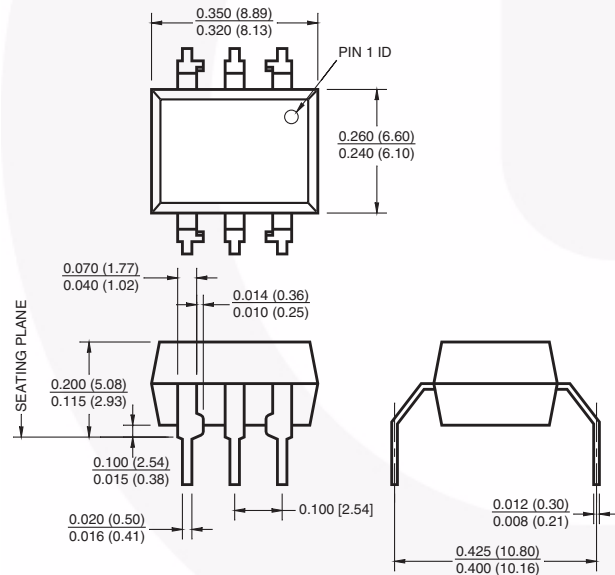
Through Hole



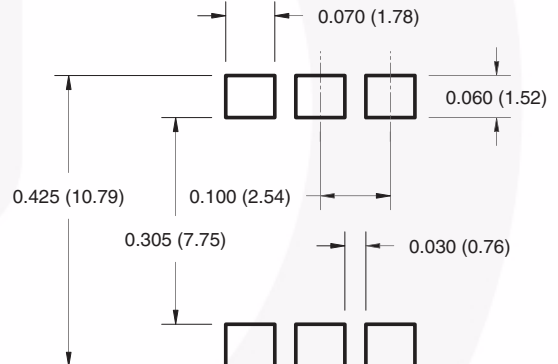
Surface Mount



0.4" Lead Spacing



Recommended Pad Layout for Surface Mount Leadform



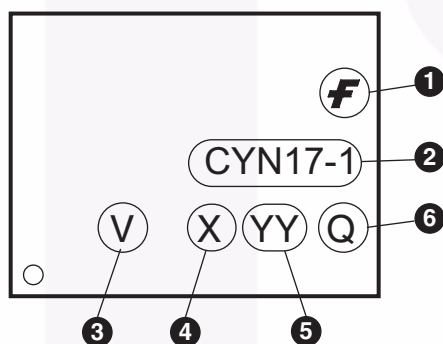
Note:

All dimensions are in inches (millimeters)

Ordering Information

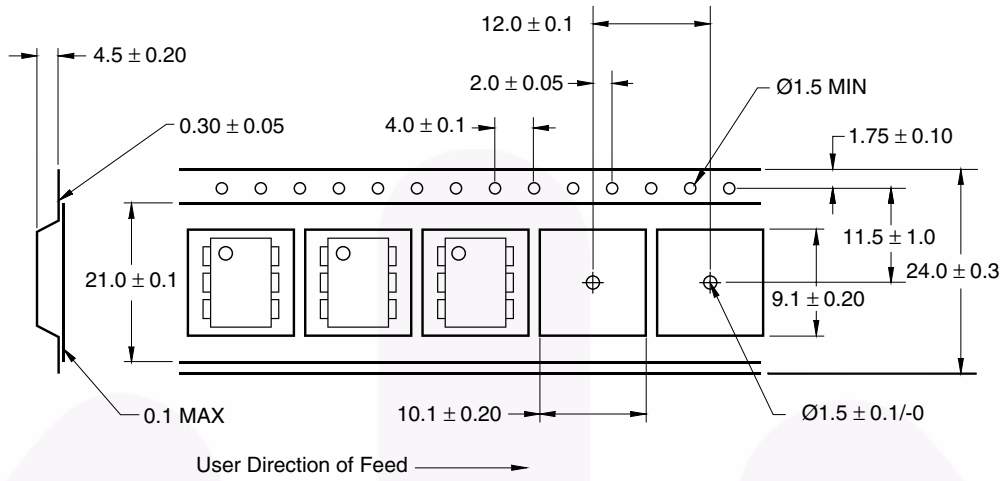
Option	Order Entry Identifier (Example)	Description
No option	CYN171M	Standard Through Hole Device
S	CYN171SM	Surface Mount Lead Bend
SR2	CYN171SR2M	Surface Mount; Tape and Reel
T	CYN171TM	0.4" Lead Spacing
V	CYN171VM	VDE 0884
TV	CYN171TVM	VDE 0884, 0.4" Lead Spacing
SV	CYN171SVM	VDE 0884, Surface Mount
SR2V	CYN171SR2VM	VDE 0884, Surface Mount, Tape and Reel

Marking Information

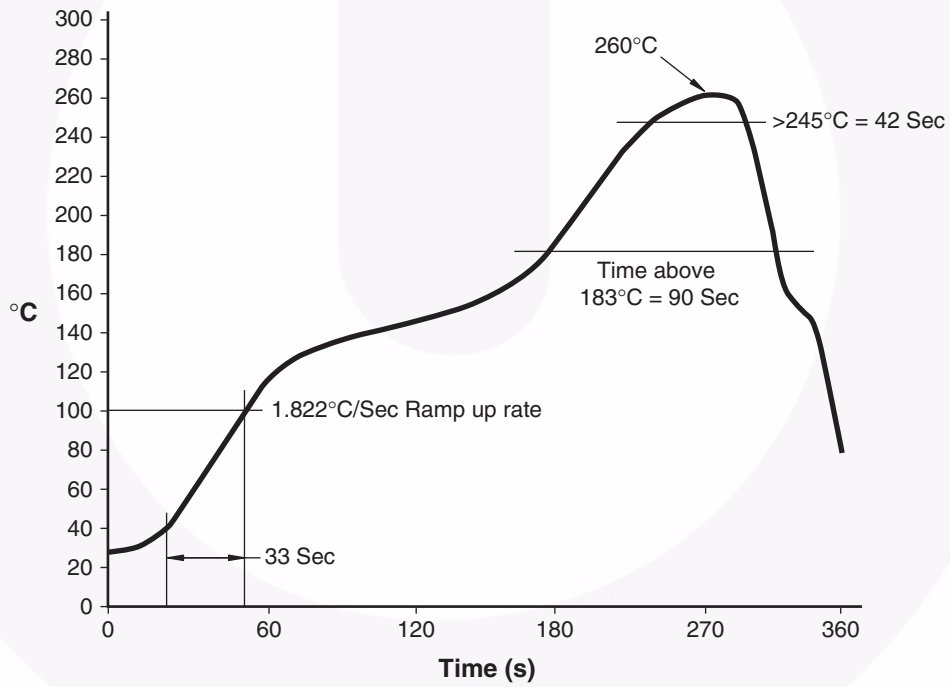


Definitions	
1	Fairchild logo
2	Device number
3	VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table)
4	One digit year code, e.g., '7'
5	Two digit work week ranging from '01' to '53'
6	Assembly package code

Carrier Tape Specification







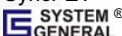
Reflow Profile





TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

ACEx®	FPS™	PDP SPM™	The Power Franchise®
Build it Now™	F-PFS™	Power-SPM™	the power franchise
CorePLUS™	FRFET®	PowerTrench®	TinyBoost™
CorePOWER™	Global Power Resource™	Programmable Active Droop™	TinyBuck™
CROSSVOLT™	Green FPS™	QFET®	TinyLogic™
CTL™	Green FPS™ e-Series™	QS™	TINYOPTO™
Current Transfer Logic™	GTO™	Quiet Series™	TinyPower™
EcoSPARK®	IntelliMAX™	RapidConfigure™	TinyPWM™
EfficientMax™	ISOPLANAR™	Saving our world, 1mW at a time™	TinyWire™
EZSWITCH™ *	MegaBuck™	SmartMax™	μSerDes™
 ™	MICROCOUPLER™	SMART START™	
 ™	MicroFET™	SPM®	UHC®
Fairchild®	MicroPak™	STEALTH™	Ultra FRFET™
Fairchild Semiconductor®	MillerDrive™	SuperFET™	UniFET™
FACT Quiet Series™	MotionMax™	SuperSOT™-3	VCX™
FACT®	Motion-SPM™	SuperSOT™-6	VisualMax™
FAST®	OPTOLOGIC®	SuperSOT™-8	
FastvCore™	OPTOPLANAR®	SupreMOS™	
FlashWriter®		SyncFET™	
			

* EZSWITCH™ and FlashWriter® are trademarks of System General Corporation, used under license by Fairchild Semiconductor.

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
2. A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	This datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

Rev. I34